## IN THE SPECIFICATION:

Page 19, line 21 (or in the patent application publication 2003/0008500: column 5, paragraph 0052, line 2): Please replace the reference to Fig. 6A to a reference to Fig. 7A.

a

A chuck 608 movably supports a substrate 610. In Fig. 7A, the chuck 608 and the substrate 610 are elevated and ready for deposition. The substrate 610 is positioned inside the chamber. Suitable processing gas is introduced into the chamber through the inlets 604, and a pulsed plasma controller 605 is periodically turned on in accordance with a process activation switch to drive the desired process.